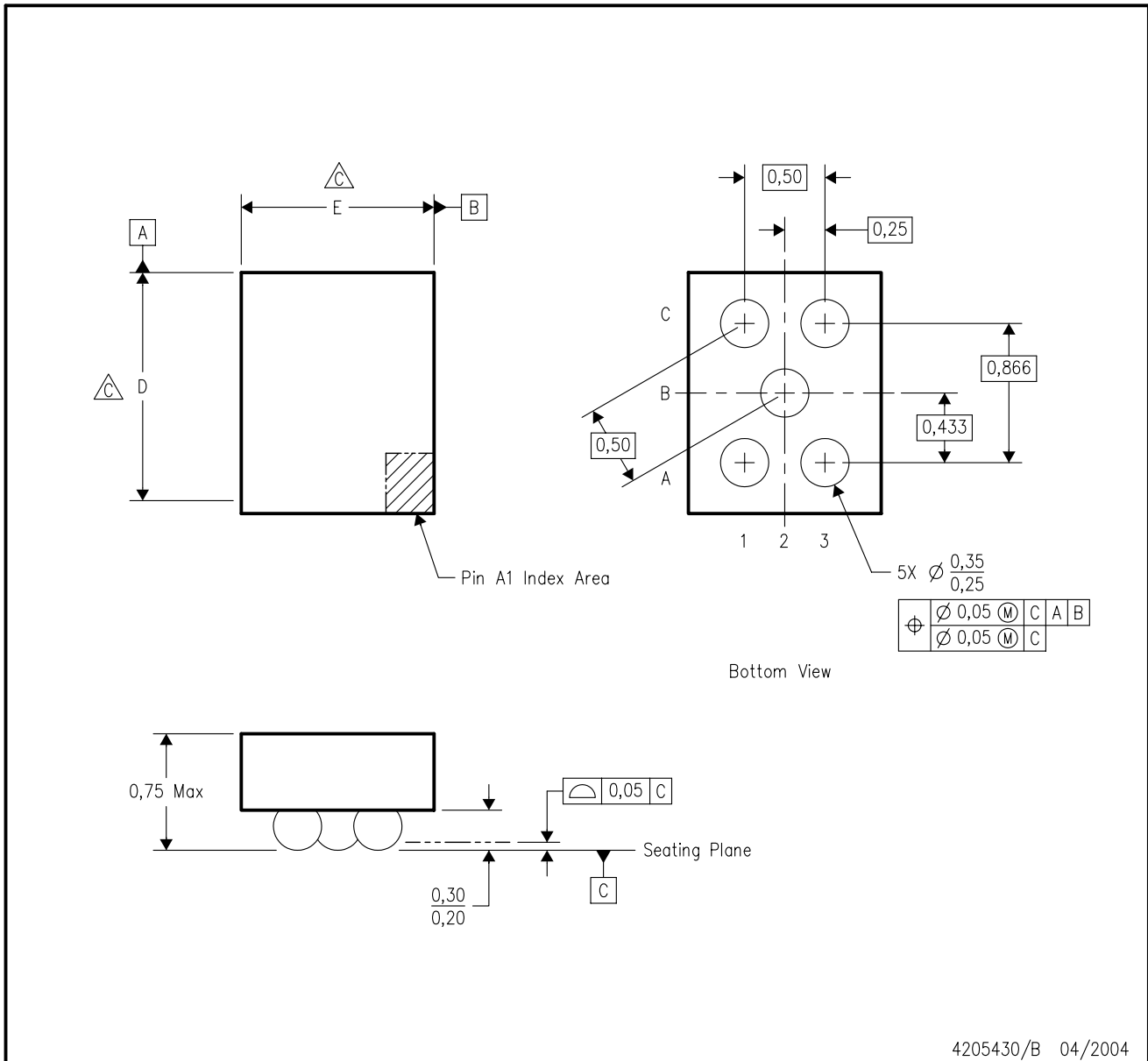


YEU (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- Notes:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Devices in this YEU package can have dimension D ranging from 1.25 to 1.75 and dimension E ranging from 0.95 to 1.45. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
 - D. NanoStar™ package configuration.
 - E. This package contains tin-lead (SnPb) balls. Refer to the 5 YZU package (drawing 4205678) for lead-free balls.

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